

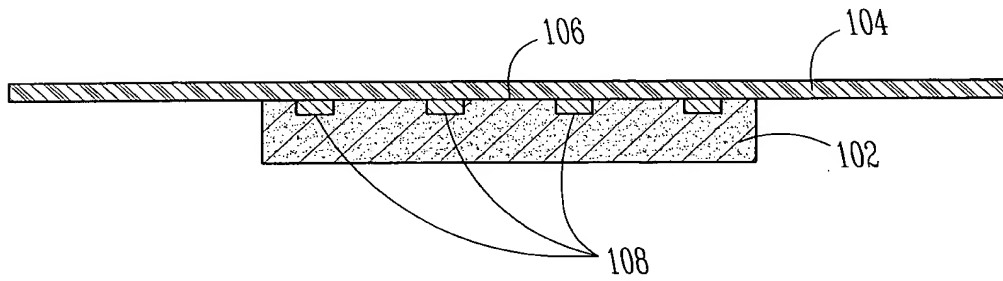


TITLE: PROCESS FOR FORMING A DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGES UTILIZING INTERMEDIATE STRUCTURES

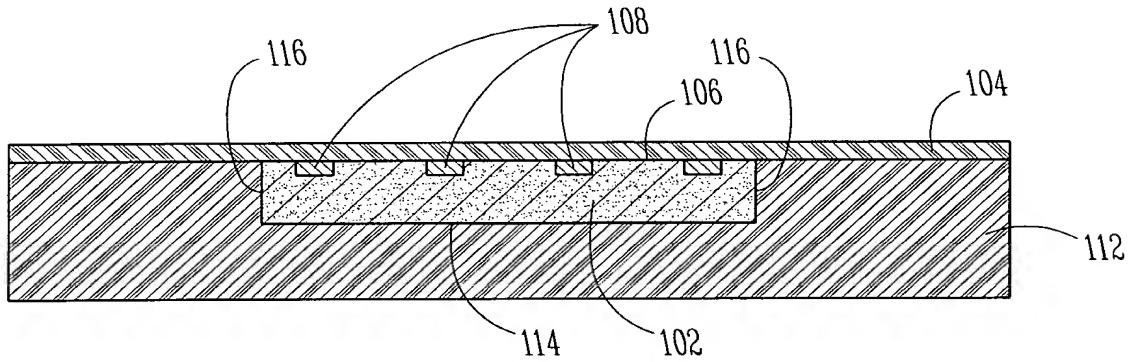
INVENTOR NAME: Xiao-Chun Mu et al.

SERIAL NO.: 09/661,899

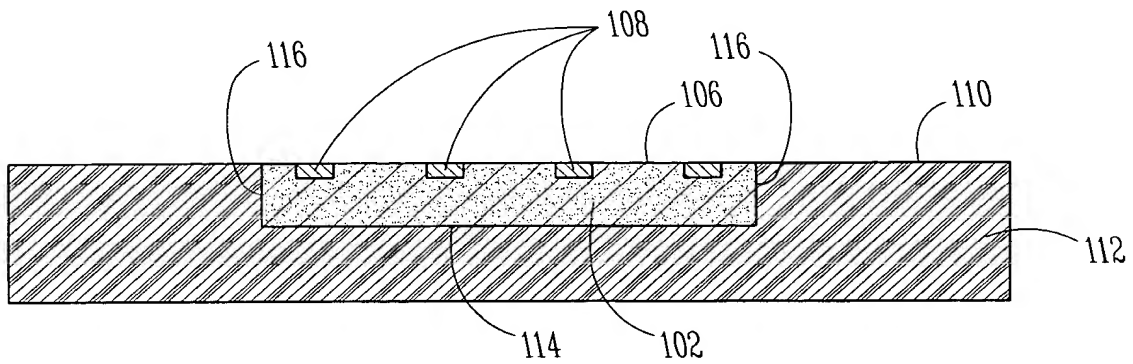
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*Fig. 1A*



*Fig. 1B*



*Fig. 1C*

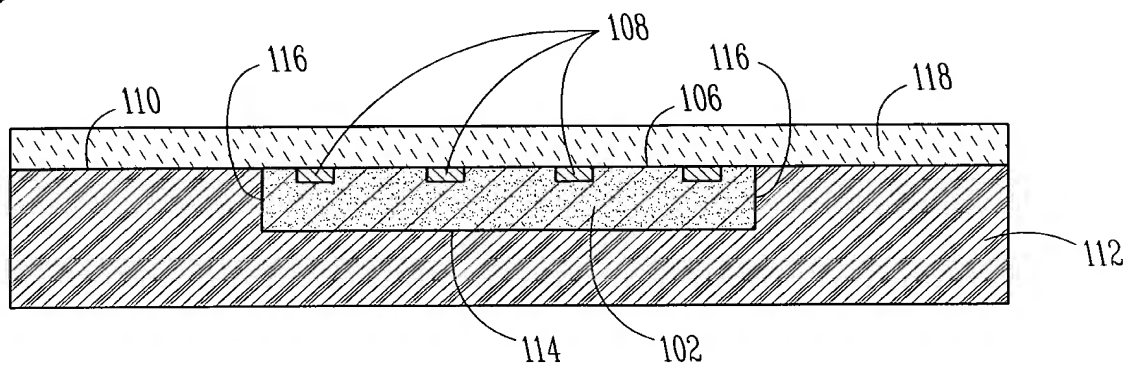
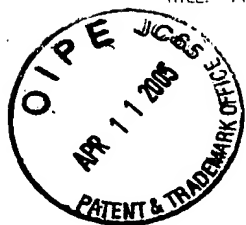


Fig. 1D

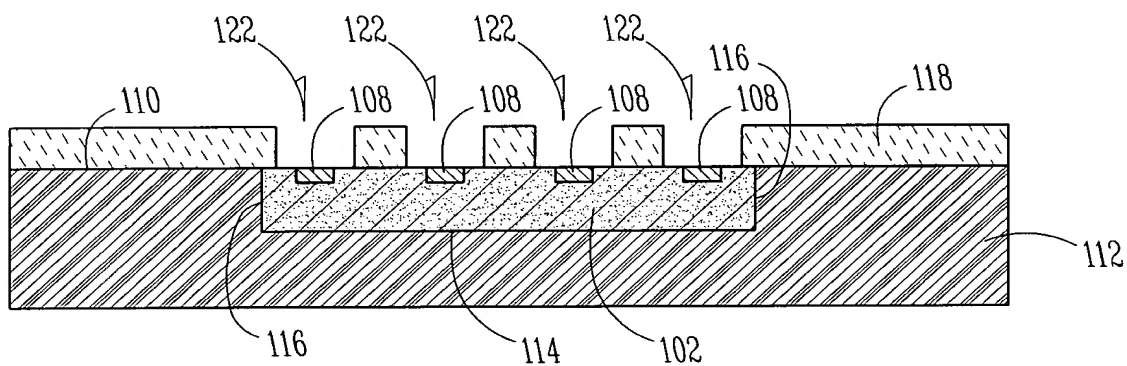


Fig. 1E

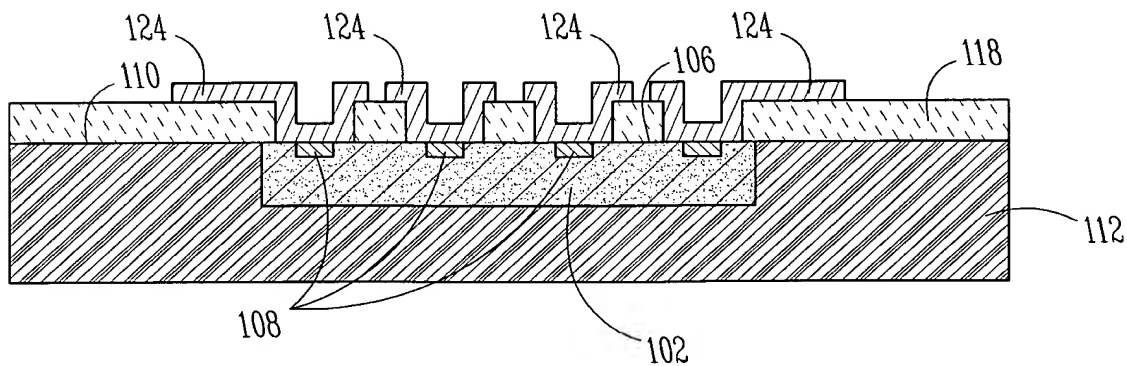
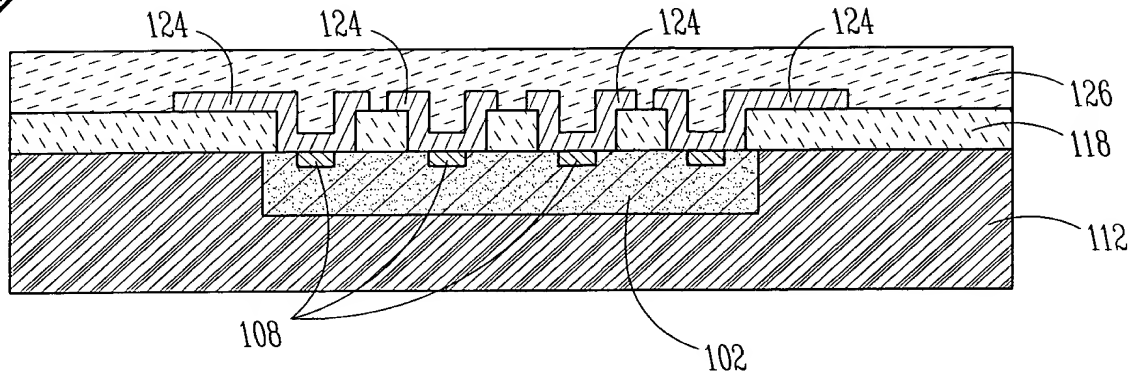
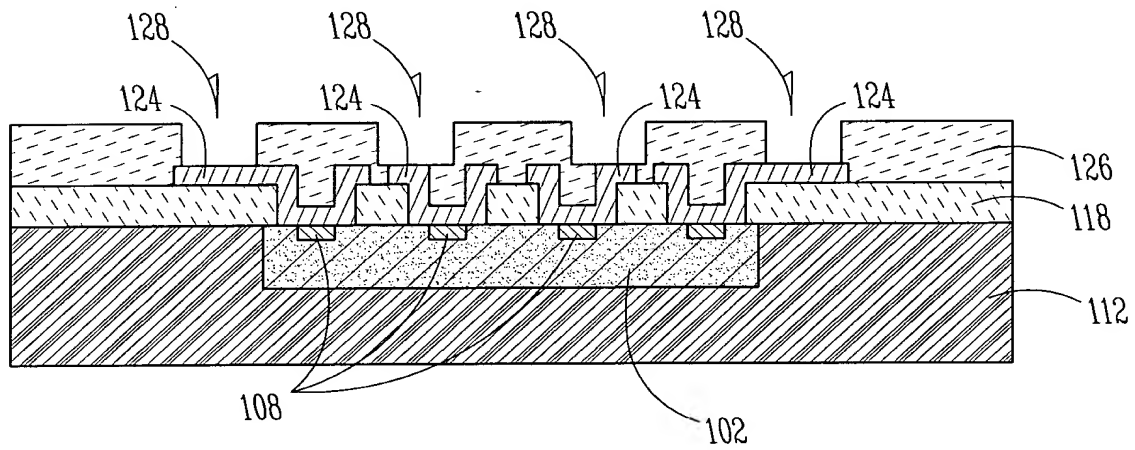


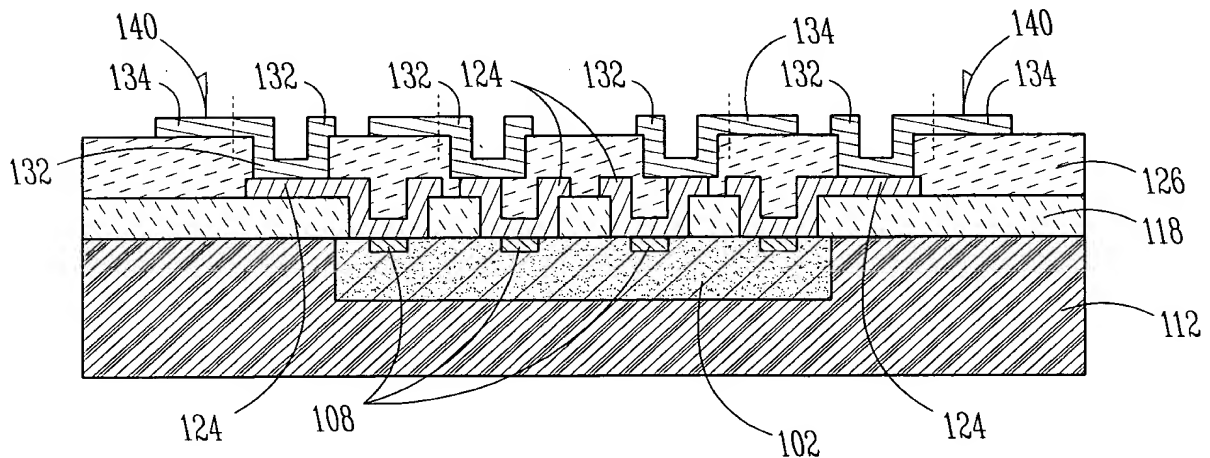
Fig. 1F



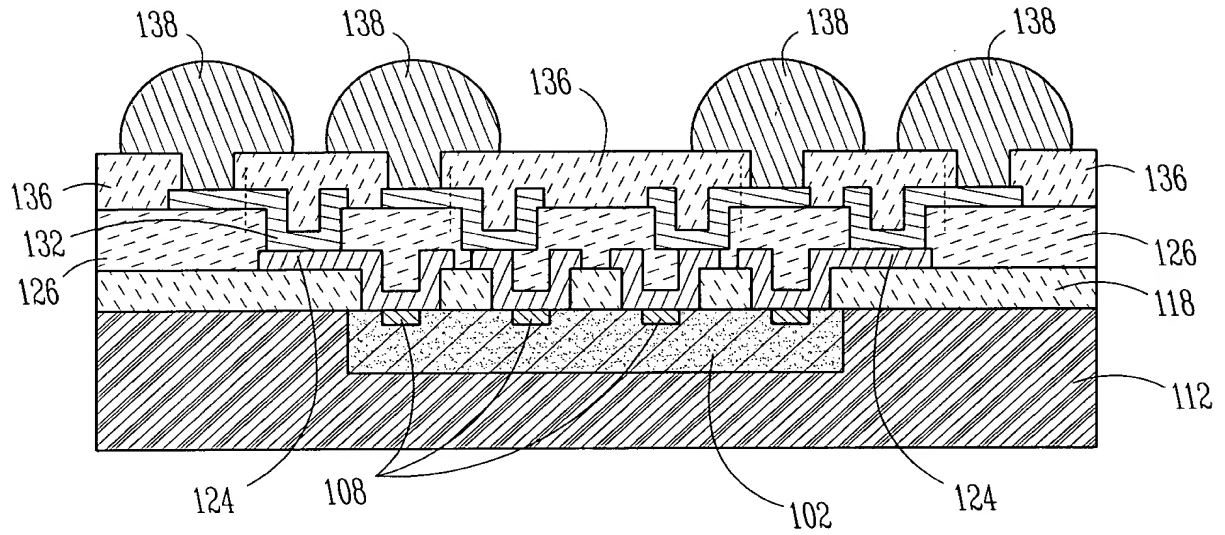
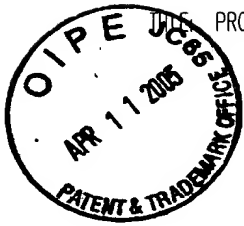
*Fig. 1G*



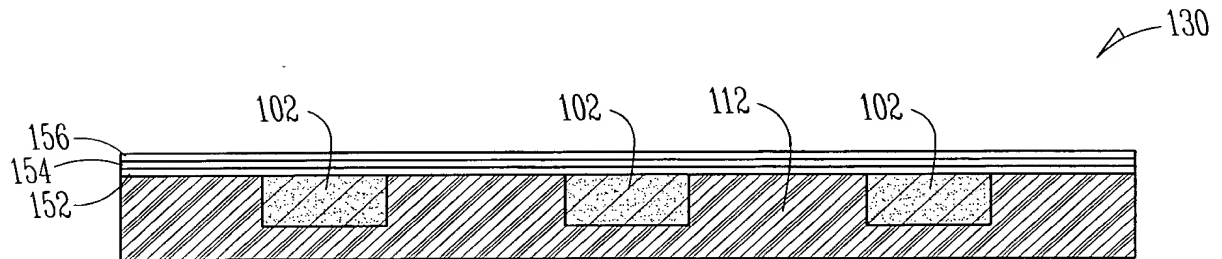
*Fig. 1H*



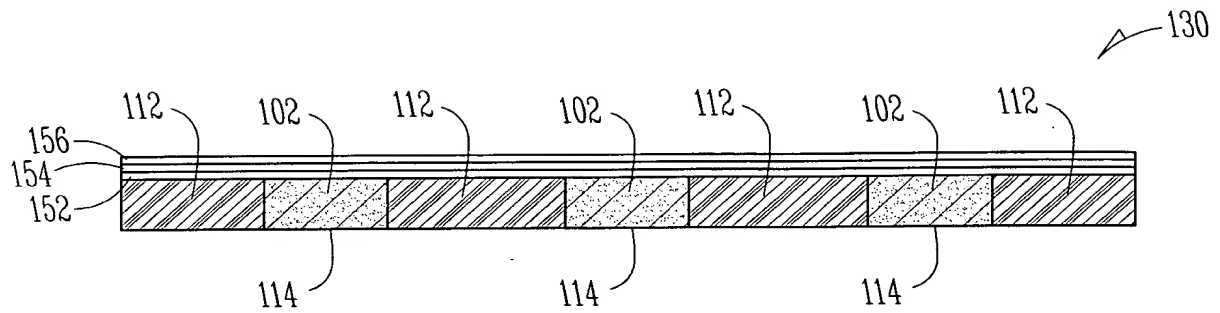
*Fig. 1I*



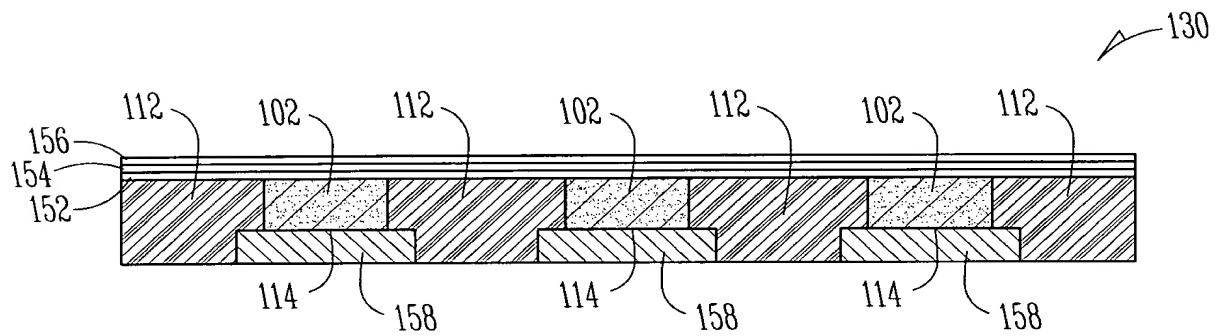
*Fig. 1J*



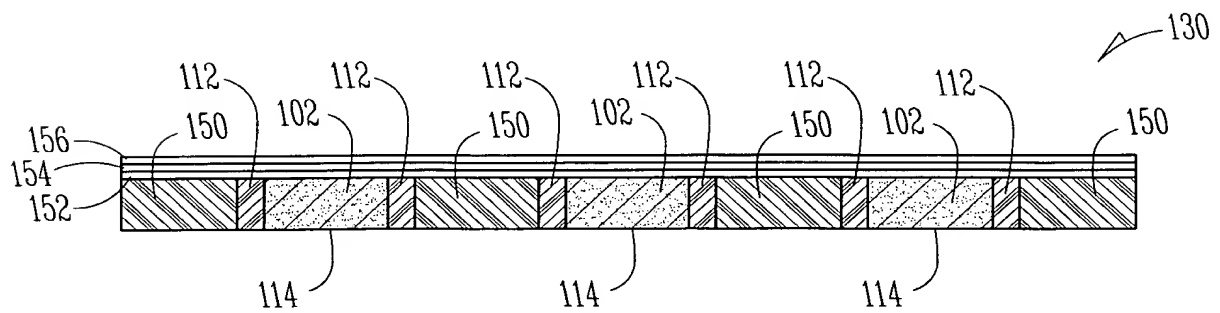
*Fig. 2*



*Fig. 3*



*Fig. 4*



*Fig. 5*

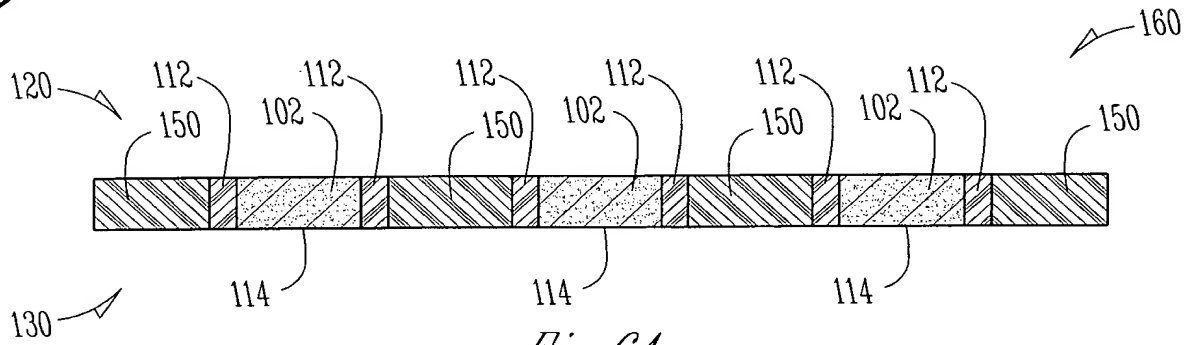
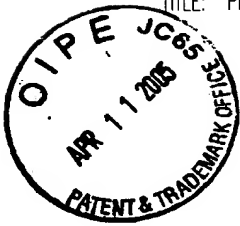


Fig. 6A

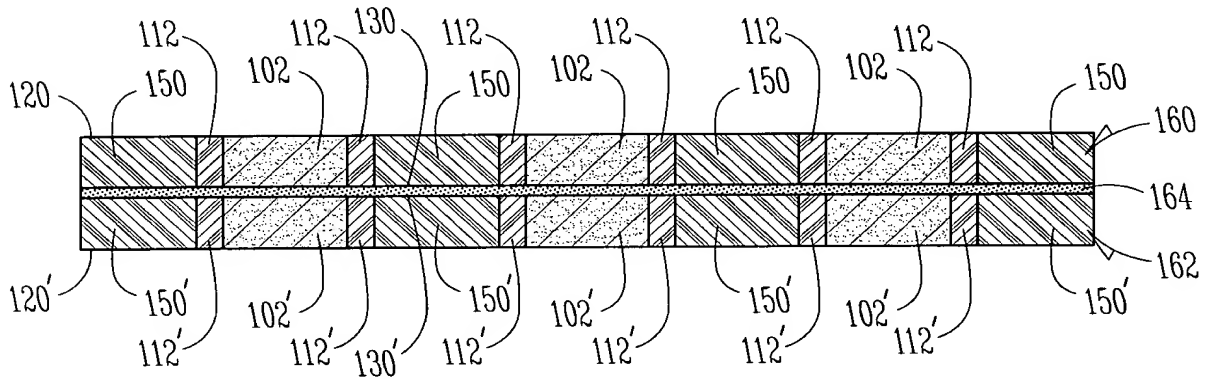


Fig. 6B

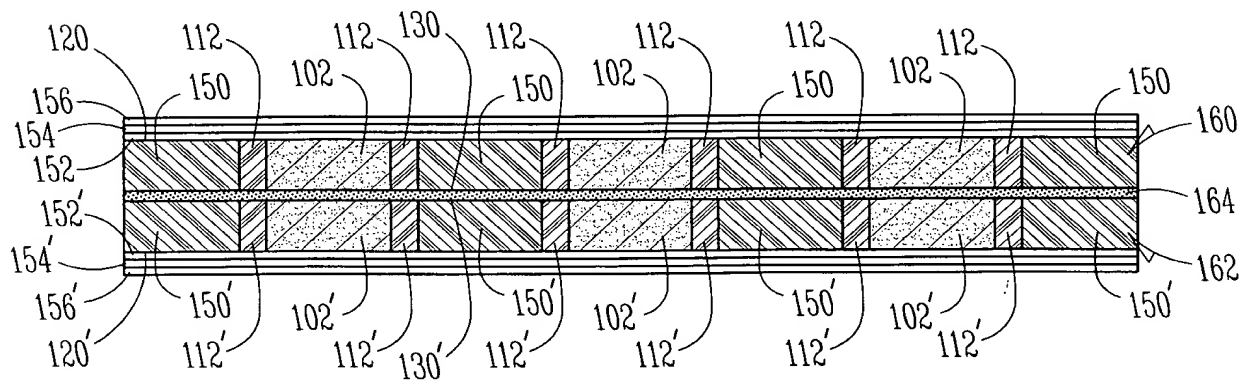
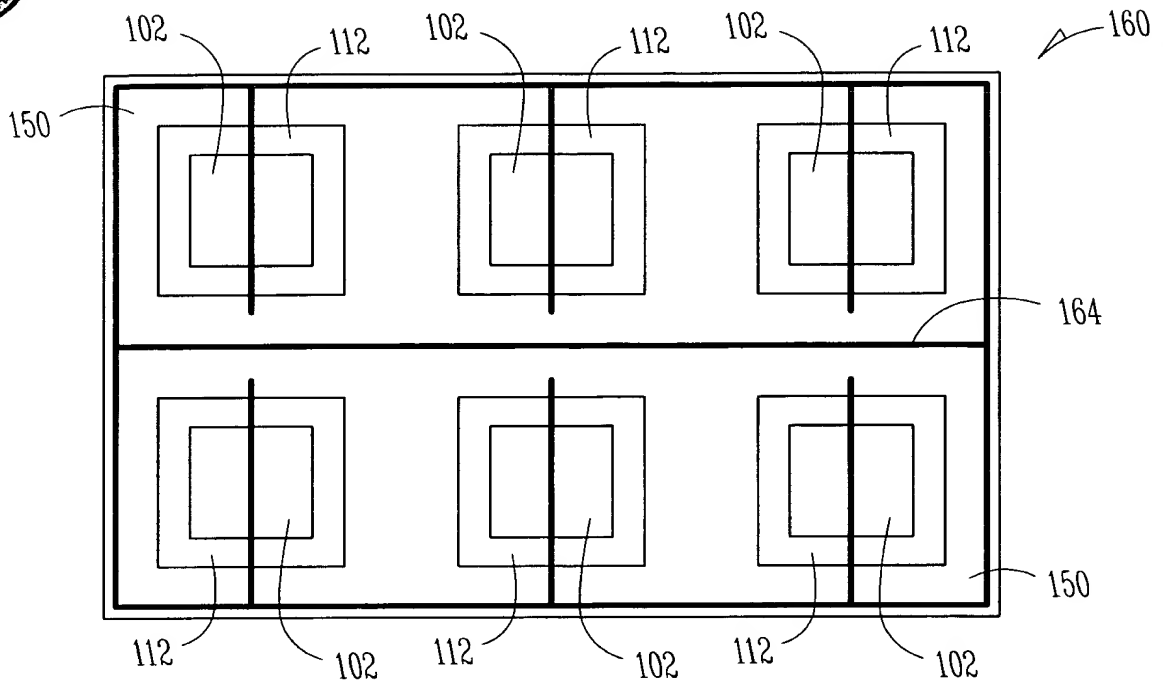
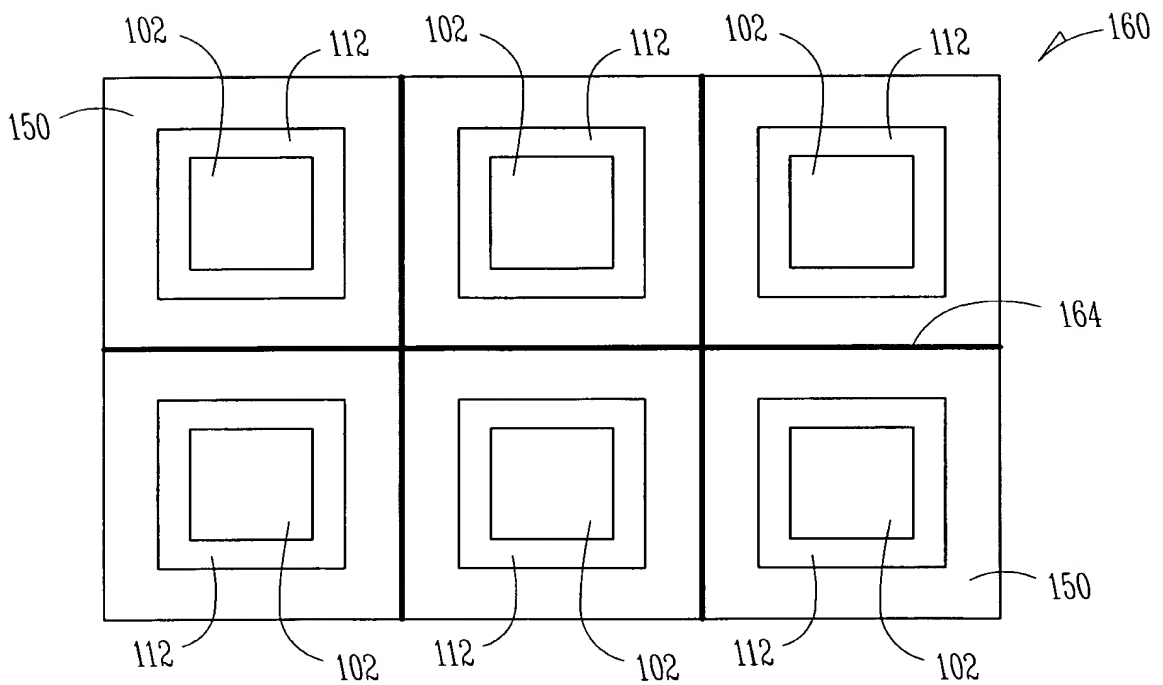


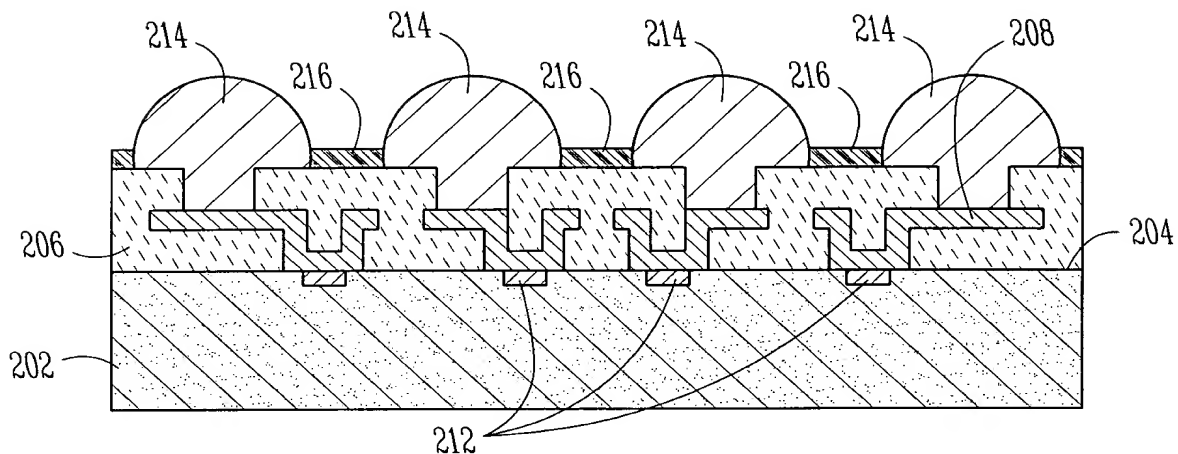
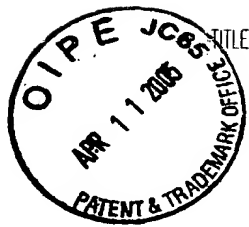
Fig. 6C



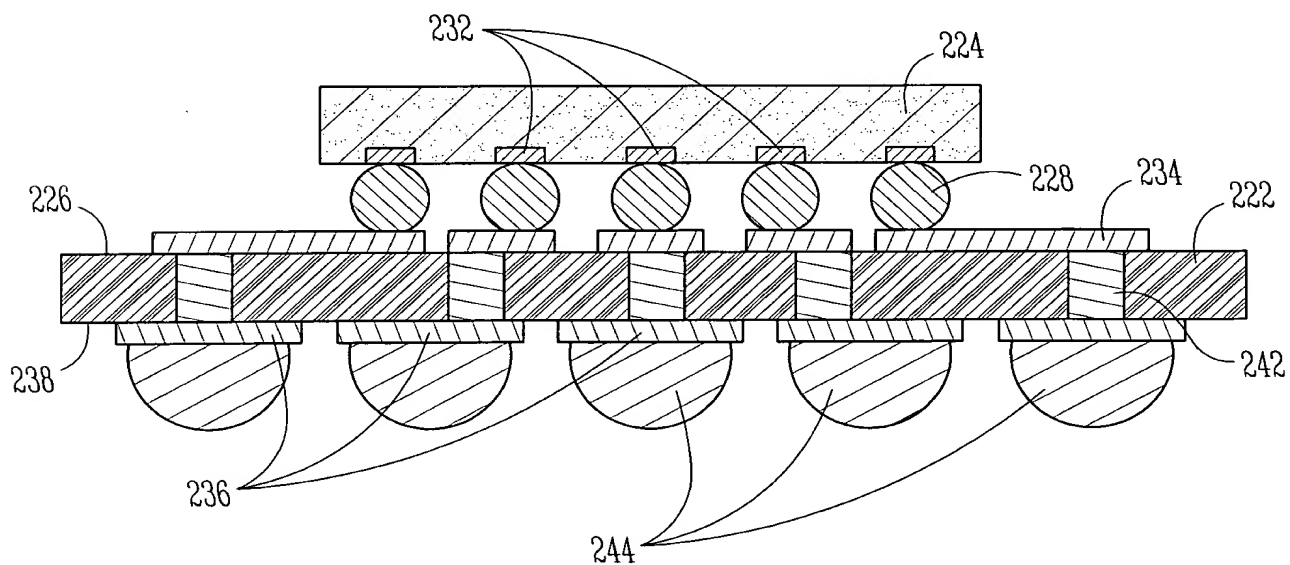
*Fig. 7*



*Fig. 8*

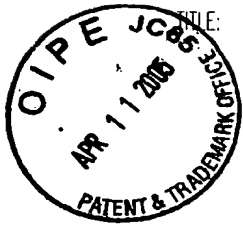


*Fig. 9 (Prior Art)*



*Fig. 10 (Prior Art)*



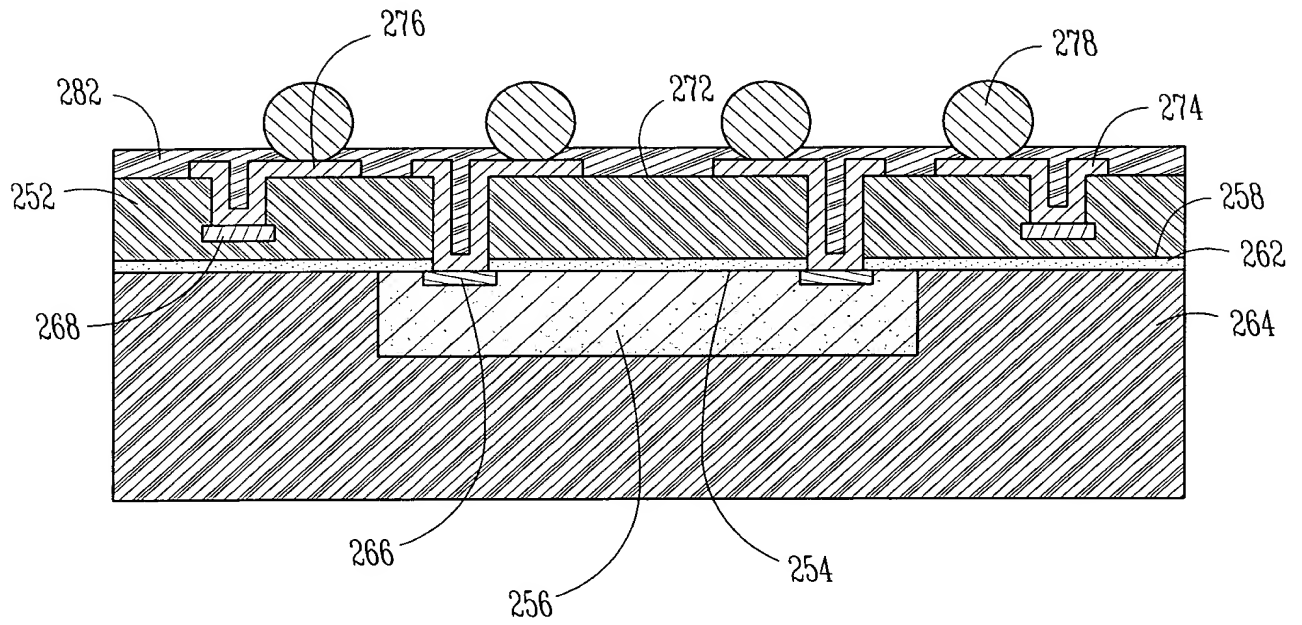


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*Fig. 11 (Prior Art)*